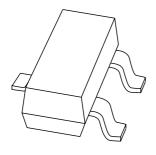
DISCRETE SEMICONDUCTORS

DATA SHEET



PBSS4350T 50 V; 3 A NPN low V_{CEsat} (BISS) transistor

Product data sheet Supersedes data of 2002 Aug 08 2004 Jan 09



50 V; 3 A NPN low V_{CEsat} (BISS) transistor

PBSS4350T

FEATURES

- Low collector-emitter saturation voltage V_{CEsat} and corresponding low R_{CEsat}
- · High collector current capability
- · High collector current gain
- Improved efficiency due to reduced heat generation.

APPLICATIONS

- · Power management applications
- Low and medium power DC/DC convertors
- · Supply line switching
- · Battery chargers
- Linear voltage regulation with low voltage drop-out (LDO).

DESCRIPTION

NPN low V_{CEsat} transistor in a SOT23 plastic package. PNP complement: PBSS5350T.

MARKING

TYPE NUMBER	MARKING CODE(1)
PBSS4350T	ZC*

Note

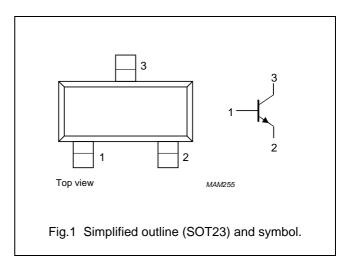
- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

QUICK REFERENCE DATA

SYMBOL	YMBOL PARAMETER		UNIT
V _{CEO}	V _{CEO} collector-emitter voltage		V
I _C	2	Α	
I _{CRP} repetitive peak collector current		3	А
R _{CEsat} equivalent on-resistance		130	mΩ

PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



ORDERING INFORMATION

TYPE		PACKAGE			
NUMBER	NAME	DESCRIPTION VERSION			
PBSS4350T	_	plastic surface mounted package; 3 leads			

50 V; 3 A NPN low V_{CEsat} (BISS) transistor

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	50	V
V_{CEO}	collector-emitter voltage	open base	_	50	٧
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _C	collector current (DC)		_	2	Α
I _{CRP}	repetitive peak collector current	note 1	_	3	Α
I _{CM}	peak collector current	single peak	_	5	Α
I _B	base current (DC)		_	0.5	Α
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 2	_	300	mW
		T _{amb} ≤ 25 °C; note 3	_	480	mW
		T _{amb} ≤ 25 °C; note 4	_	540	mW
		T _{amb} ≤ 25 °C; notes 1 and 2	-	1.2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Operated under pulsed conditions: pulse width $t_p \le 100$ ms; duty cycle $\delta \le 0.25$.
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint.
- 3. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm².
- 4. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to	in free air; note 1	417	K/W
	ambient	in free air; note 2	260	K/W
		in free air; note 3	230	K/W
		in free air; notes 1 and 4	104	K/W

Notes

- Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint.
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm².
- 3. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².
- 4. Operated under pulsed conditions: pulse width $t_p \le 100$ ms; duty cycle $\delta \le 0.25$.

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

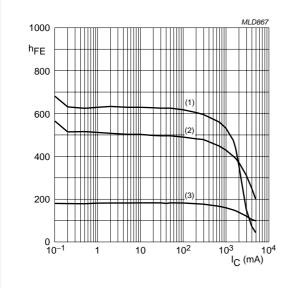
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO} collector-base cut-off current I		I _E = 0; V _{CB} = 50 V	_	_	100	nA
		I _E = 0; V _{CB} = 50 V; T _j = 150 °C	_	_	50	μА
I _{EBO}	emitter-base cut-off current	I _C = 0; V _{EB} = 5 V	_	_	100	nA
h _{FE}	DC current gain	I _C = 100 mA; V _{CE} = 2 V	300	-	_	
		I _C = 500 mA; V _{CE} = 2 V	300	_	_	
		I _C = 1 A; V _{CE} = 2 V; note 1	300	_	_	
		I _C = 2 A; V _{CE} = 2 V; note 1	200	_	_	
		I _C = 3 A; V _{CE} = 2 V; note 1	100	_	_	
V _{CEsat}	CEsat collector-emitter saturation voltage	I _C = 500 mA; I _B = 50 mA	-	_	80	mV
		I _C = 1 A; I _B = 50 mA	_	_	160	mV
		I _C = 2 A; I _B = 100 mA; note 1	-	_	280	mV
		I _C = 2 A; I _B = 200 mA; note 1	_	_	260	mV
		I _C = 3 A; I _B = 300 mA; note 1	_	_	370	mV
R _{CEsat}	equivalent on-resistance	I _C = 2 A; I _B = 200 mA; note 1	_	100	130	mΩ
V _{BEsat}	base-emitter saturation	I _C = 2 A; I _B = 100 mA; note 1	_	_	1.1	V
	voltage	I _C = 3 A; I _B = 300 mA; note 1	-	_	1.2	V
V _{BEon}	base-emitter turn-on voltage	I _C = 1 A; V _{CE} = 2 V; note 1	1.2	_	_	V
f _T	transition frequency	$I_C = 100 \text{ mA}; V_{CE} = 5 \text{ V};$ f = 100 MHz	100	_	_	MHz
C _c	collector capacitance	$I_E = I_e = 0$; $V_{CB} = 10 \text{ V}$; $f = 1 \text{ MHz}$	_	_	25	pF

Note

1. Pulse test: $t_p \leq 300~\mu s;~\delta \leq 0.02.$

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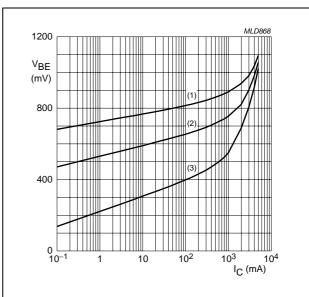
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 $V_{CE} = 2 V$.

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

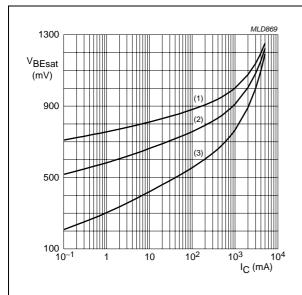
Fig.2 DC current gain as a function of collector current; typical values.



 $V_{CE} = 2 V$.

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

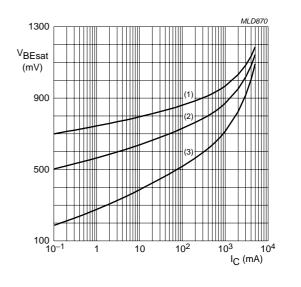
Fig.3 Base-emitter voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 10.$

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

Fig.4 Base-emitter saturation voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 20.$

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

Fig.5 Base-emitter saturation voltage as a function of collector current; typical values.

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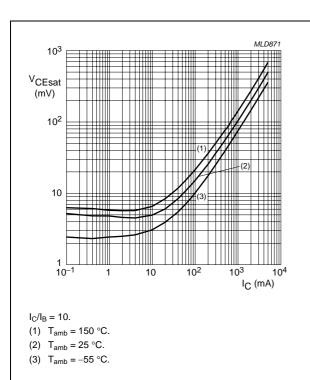
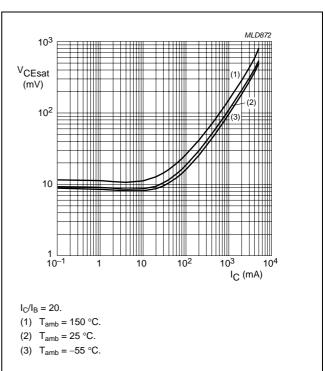
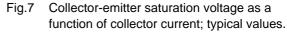
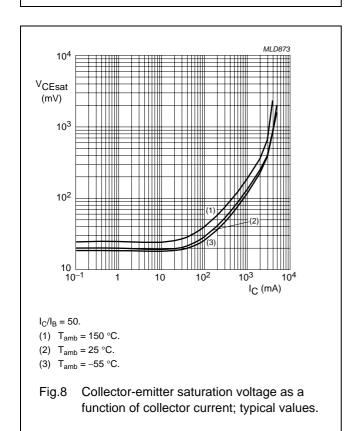
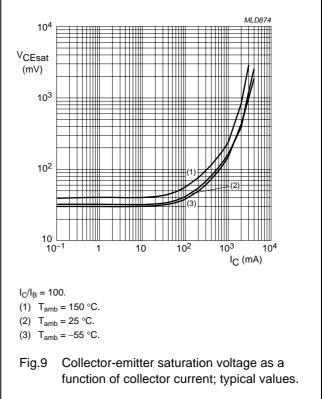


Fig.6 Collector-emitter saturation voltage as a function of collector current; typical values.









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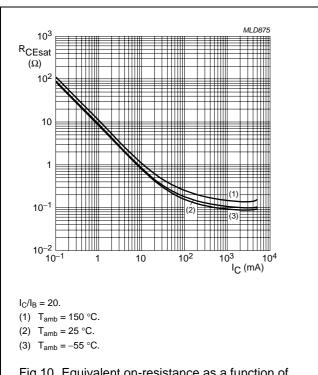


Fig.10 Equivalent on-resistance as a function of collector current; typical values.

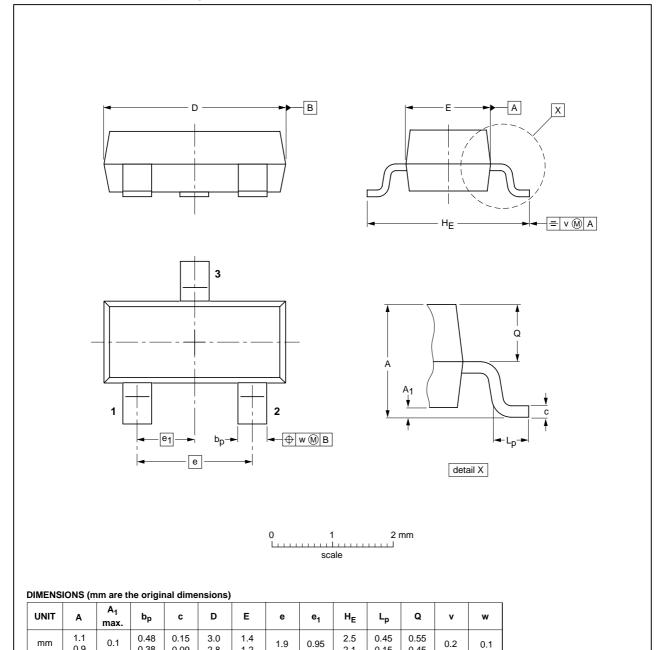
50 V; 3 A NPN low V_{CEsat} (BISS) transistor

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PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



OUTLINE		REFERENCES EUROPEAN ISS			ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT23		TO-236AB				-04-11-04 06-03-16

0.15

2004 Jan 09 8

50 V; 3 A NPN low V_{CEsat} (BISS) transistor

PBSS4350T

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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- The product status of device(s) described in this document may have changed since this document was published
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